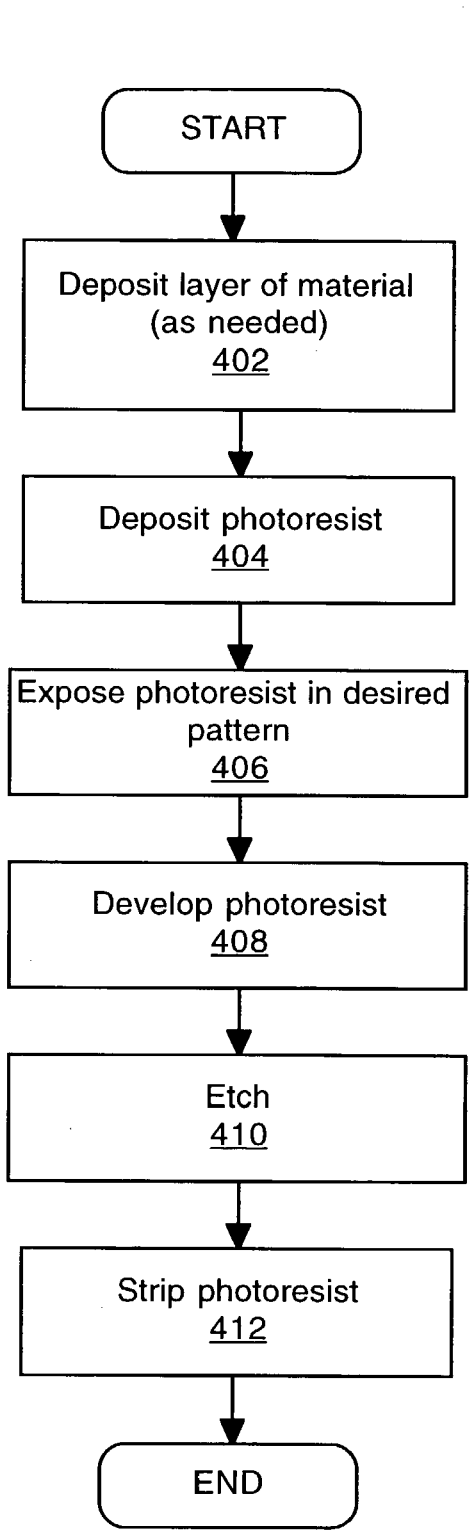
400
START
Deposit layer of material (as needed) 402
Deposit photoresist 404
Expose photoresist in desired pattern 406
Develop photoresist 408
Etch 410
Strip photoresist 412
END

Fig. 4